

/ Descriptions

1.0A ABF
1.0A Surface Mount Glass Passivated Bridge Rectifier, ABF thin package.

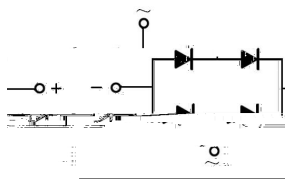
/ Features

1000V 1.0A
Glass Passivated Chip Junction,Reverse Voltage: 1000V,Forward Current:1.0A, Fast reverse recovery time,Designed for Surface Mount Application.Halogen free product.

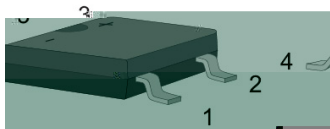
/ Applications

General purpose.

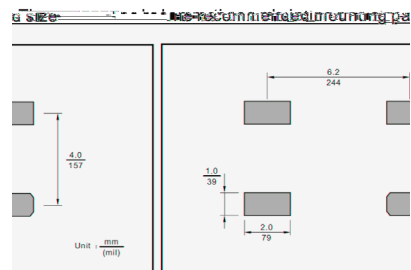
/ Equivalent Circuit



/ Pinning



PIN	DESCRIPTION
1	Input Pin (~)
2	Input Pin (~)
3	Output Anode (+)
3 GND	Output Anode



/ Marking

See Marking Instructions.

/ Absolute Maximum Ratings(Ta=25)

Parameter	Symbol	Rating	Unit
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	1000	V
Maximum RMS Voltage	V_{RMS}	700	V
Maximum DC Blocking Voltage	V_{DC}	1000	V
Average Rectified Output Current at $T_c = 125$	I_o	1.0	A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load	I_{FSM}	30	A
Typical Junction Capacitance ^{Note1}	C_j	30	pF
Typical Thermal Resistance ^{Note2}	$R_{\theta JA}$	75	/W
Operating and Storage Temperature Range	T_j, T_{stg}	-55~150	

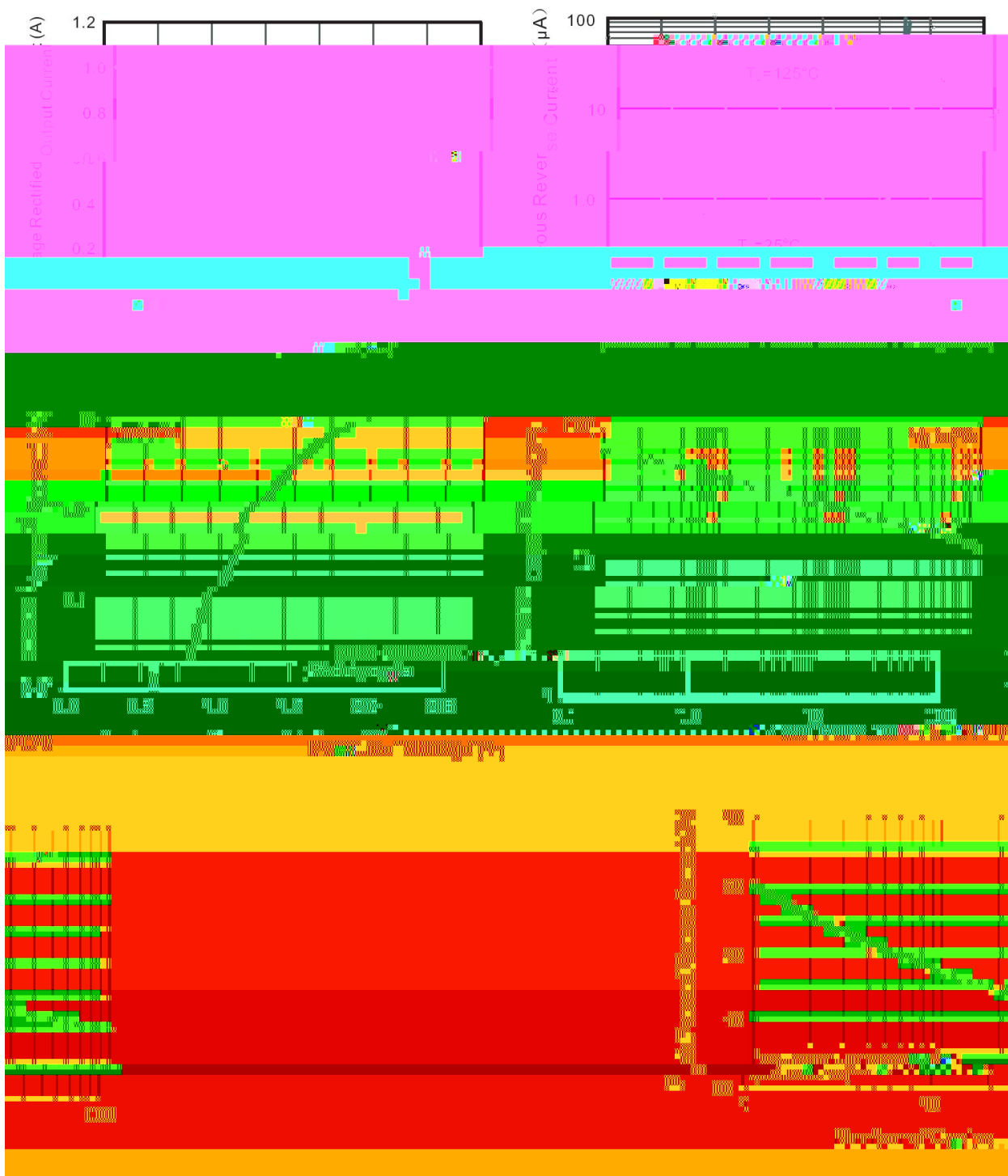
Note:

- 1.Measured at 1MHz and applied reverse voltage of 4 V D.C.
2. Mounted on glass epoxy PC board with 4 1.0" X 1.0" (2.54 X 2.54 cm) copper pad.

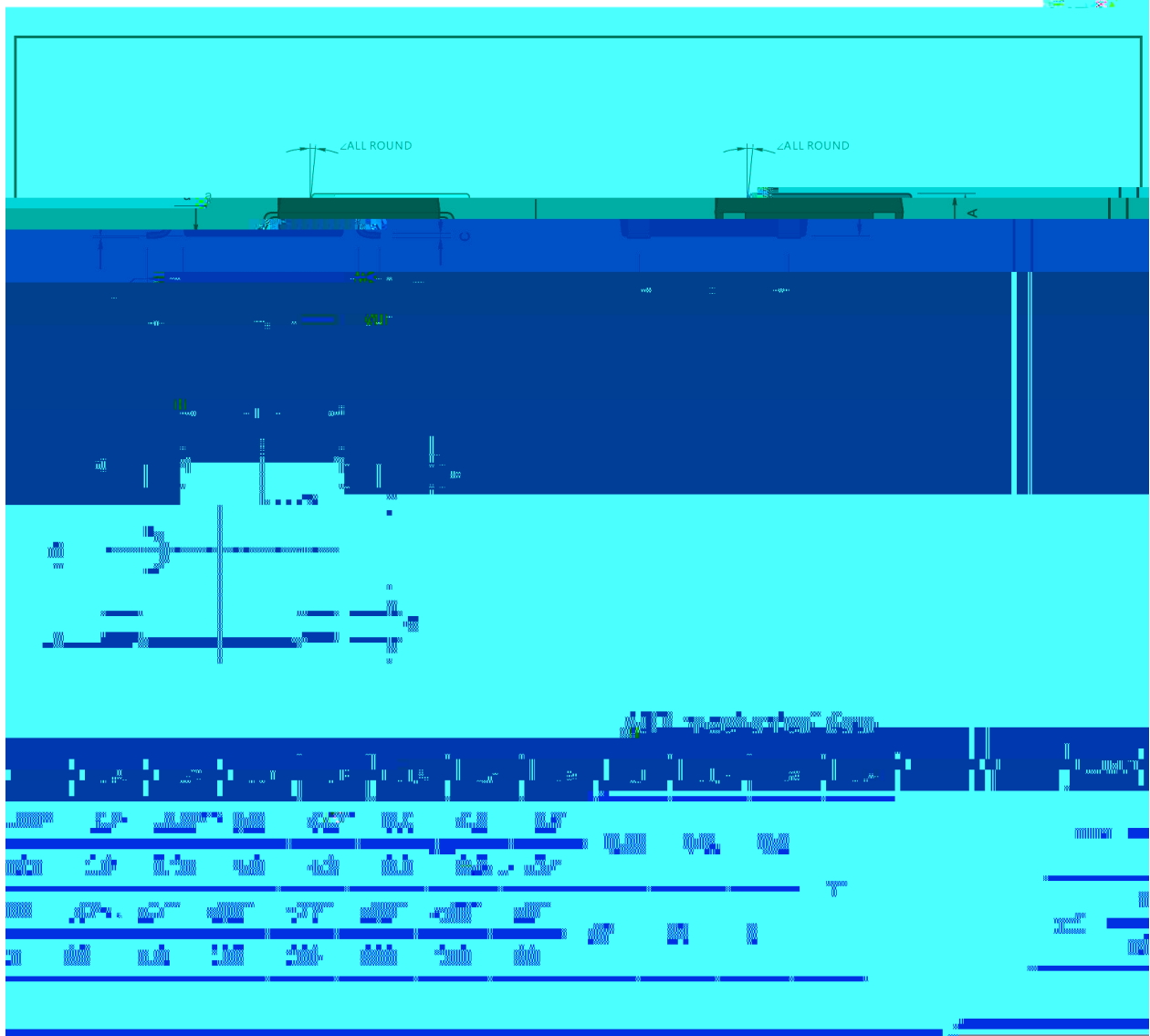
/ Electrical Characteristics(Ta=25)

Parameter	Symbol	Test Conditions	Rating	Unit
Forward Voltage per element	V_F	$I_F=1.0A$	1.3	V
Maximum DC Reverse Current at Maximum DC Blocking Voltage	I_R	$T_a=25$	5.0	μA
		$T_a=125$	50	μA
Maximum Reverse Recovery Time	t_{rr}	$I_F=0.5A$ $I_R=1.0A$ $I_{rr}=0.25A$	200	ns

/ Electrical Characteristic Curve

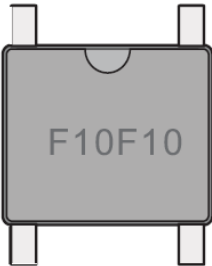


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/ Marking Instructions

Marking

ing code	Type number	Mark
		

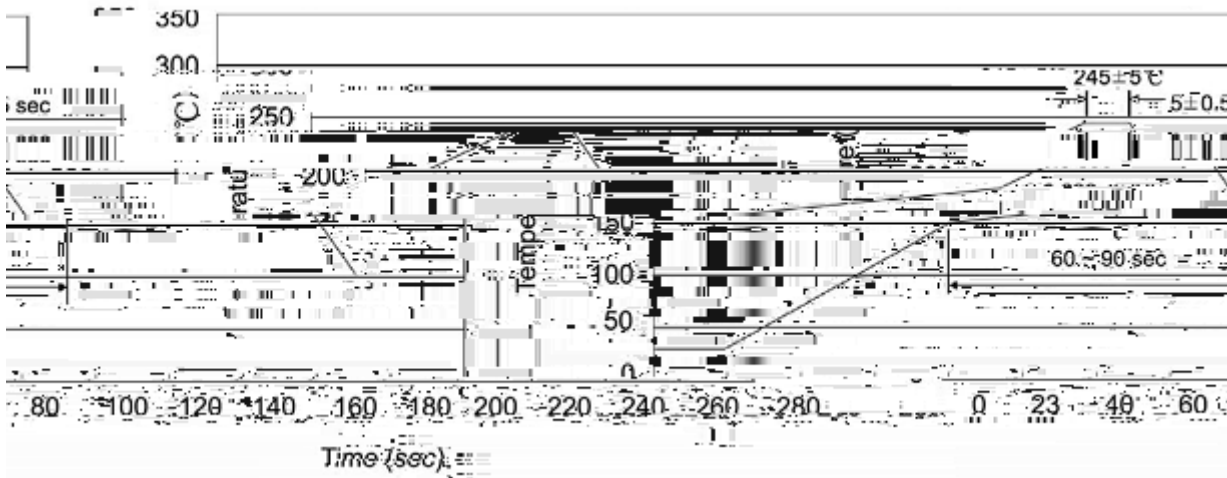
/ Marking Instructions

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() / Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- | | | | | | |
|---|-------|-----|-----------|---|--------------------------------------|
| 1 | 25 | 150 | 60 | 90sec; | 1.Preheating:25~150 , Time:60~90sec. |
| 2 | 245±5 | | 5±0.5sec; | 2.Peak Temp.:245±5 , Duration:5±0.5sec. | |
| 3 | | 2 | 10 | /sec. | 3. Cooling Speed: 2~10 /sec. |

/ Resistance to Soldering Heat Test Conditions

260±5 10±1 sec. Temp.:260±5 Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type	Units					Dimension (unit mm ³)		
	5000	2	10000	5	50000	13 ×15	336X336X40	380X335X366

/ Notices